

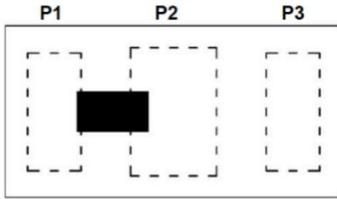
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

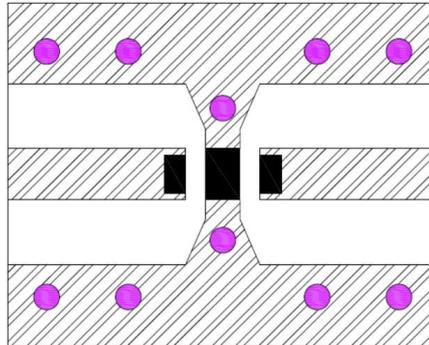
NO.	Parameter	Frequency (MHz)	SPC		
			Min.	Typ.	Max.
1	Insertion Loss (dB)	5150~5250		1.0	1.5
		5250~5330		1.0	1.5
		5490~5730		1.0	1.5
		5730~5925		1.0	1.5
2	Insertion Loss (dB) -40 ~ +90 °C	5150~5250			1.7
		5250~5330			1.7
		5490~5730			1.7
		5730~5925			1.7
3	VSWR				2.0-
4	Attenuation (dB)	700~2690	35		
		3300~3800	28		
		3800~4000	28		
		4400~4600	3.5		
		6900~7200	8		
		7200~7800	20		
		7800~9800	18		
		9800~11700	20		
14700~17850	15				
5	In/Output Impedance (Ω)			50	
Operating & Storage Condition (Component)					
Operation Temperature Range: -40°C ~ +85°C					
Storage Temperature Range: -40°C~ +85°C					
Storage Condition before Soldering (Included packaging material)					
Storage Temperature Range: +5 ~ +40 °C					
Humidity: 30 to 70% relative humidity					

Construction



PIN	Connection
1	Input port
2	GND
3	Output port

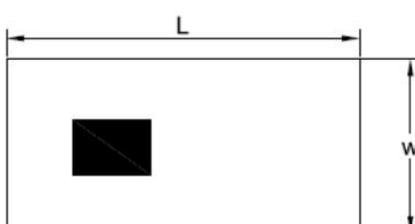
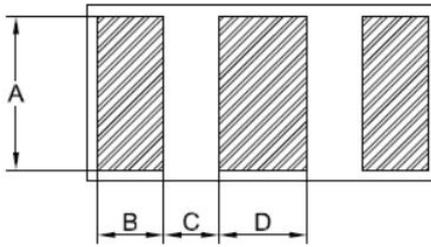
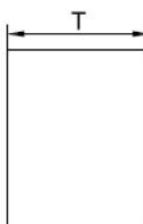
Mounting Considerations



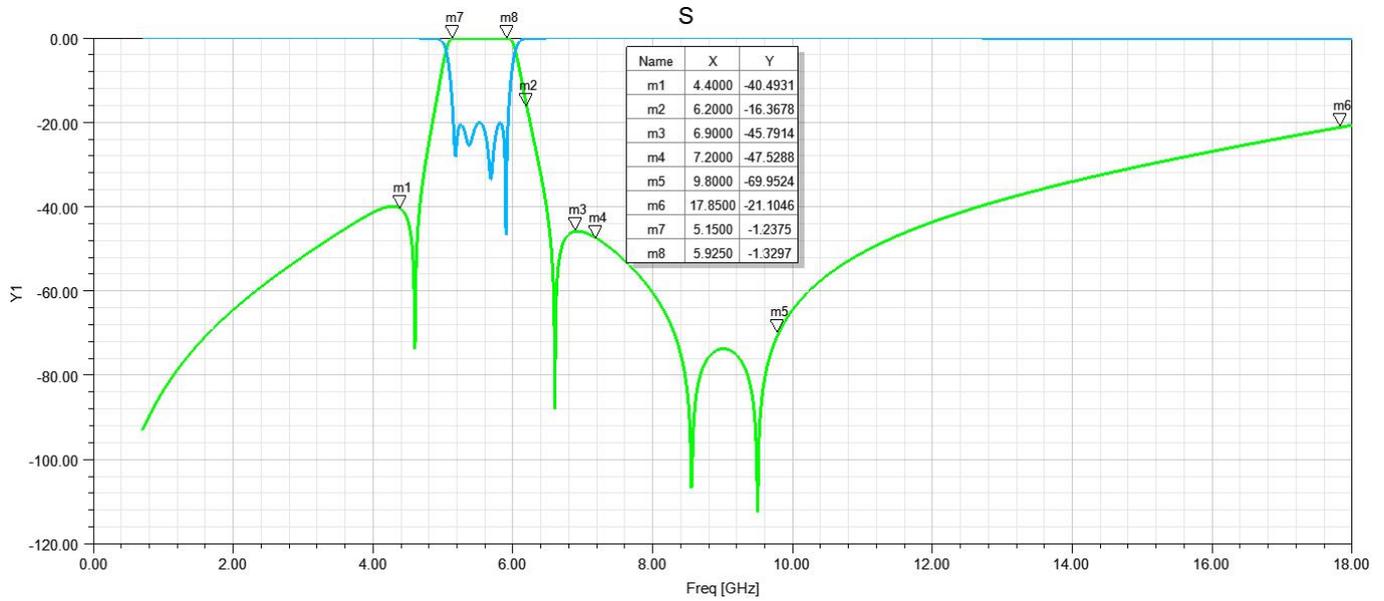
- Land
- ▨ Solder
- Through-hole

Unit: mm
 Line width to be designed to match 50 Ω characteristic impedance, depending on PCB material and thickness

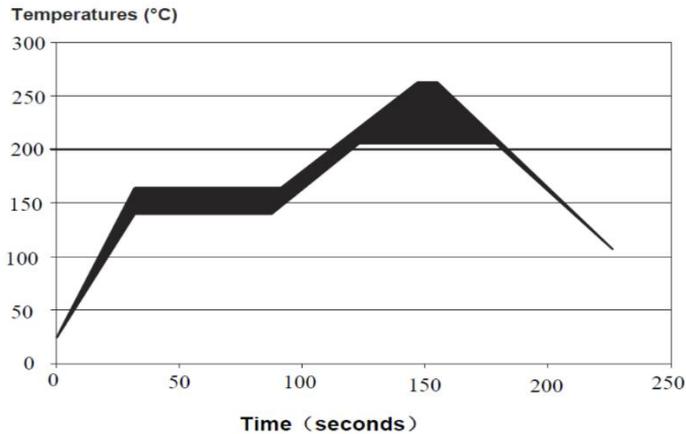
Dimensions

Figure	Symbol	Dimension (mm)
<p>TOP View</p> 	L	1.60±0.10
	W	0.80±0.10
<p>Bottom View</p> 	T	0.60±0.10
	A	0.70±0.10
<p>Side View</p> 	B	0.30±0.10
	C	0.25±0.10
	D	0.4±0.10

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.